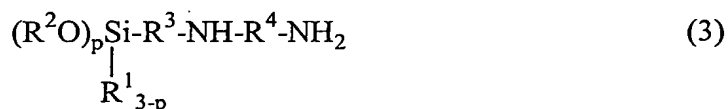


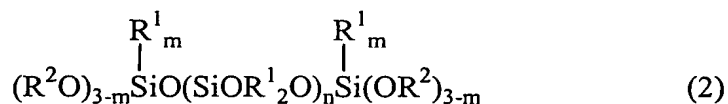
CLAIMS:

1. A method of improving adherence to an architectural part or electrical or electronic part upon exposure to steam of a room temperature curable organopolysiloxane composition, said method comprising the step of:

blending (C) 0.1 to 10 parts by weight of an organosilicon compound of the following general formula (3):



wherein R^1 is a substituted or unsubstituted monovalent hydrocarbon radical of 1 to 10 carbon atoms, R^2 is a substituted or unsubstituted monovalent hydrocarbon radical of 1 to 6 carbon atoms as defined above, R^3 is a divalent hydrocarbon radical of 1 to 10 carbon atoms, R^4 is a divalent aromatic ring-bearing hydrocarbon radical of 7 to 10 carbon atoms, and p is an integer of 1 to 3, at least one of the NH and NH_2 radicals being not directly attached to the aromatic ring in R^4 , with (A) 100 parts by weight of an organopolysiloxane of the following general formula (2):



wherein R^1 and R^2 are as defined above, n is an integer of at least 10, and m is independently an integer of 0 or 1, or both, and (B) 0.1 to 30 parts by weight of a silane compound having at least two ketoxime radicals each attached to a silicon atom in a molecule, the remaining radicals attached to silicon atoms being selected from the group consisting of

7. The method of claim 1, further comprising a filler.

5 8. The method of claim 7, wherein the filler is silica and/or carbon black.